

SYSTEM AND METHOD FOR FORMING
MOLD CAPS OVER INTEGRATED CIRCUIT DEVICES

5 ABSTRACT OF THE DISCLOSURE

 A compression molding method for forming a mold cap
over an integrated circuit structure is provided. A film
is positioned adjacent a first die structure such that a
mold block coupled to the film is located in a die cavity
10 in the first die structure. The mold block comprises
mold compound and at least substantially holding its own
shape. An integrated circuit structure including one or
more integrated circuit devices coupled to a substrate is
positioned adjacent a second die structure. At least one
15 of the first die structure and the second die structure
is moved toward the other die structure to cause the
integrated circuit structure to compress the mold block
within the die cavity in order to form a mold cap
covering at least one of the one or more integrated
20 circuit devices.